

SB220 THRU SB2200

List

深圳FMS Kinter 131 6803 0058

List.....	1
Package outline.....	2
Features.....	2
Mechanical data.....	2
Maximum ratings	2
Rating and characteristic curves.....	3
Pinning information.....	4
Marking.....	4
Taping & bulk specifications for AXIAL devices.....	4
Suggested thermal profiles for soldering processes.....	5
High reliability test capabilities.....	6

SB220 THRU SB2200

2.0A Axial Leaded Schottky Barrier Rectifiers-20V-200V

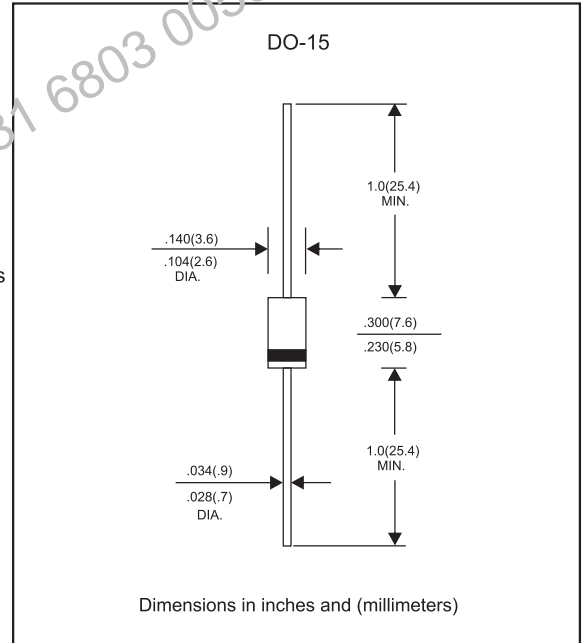
Features

- Metal silicon junction ,majority carrier conduction
- Guard ring for overvoltage protection
- Low power loss ,high efficiency
- High current capability ,Low forward voltage drop
- High surge capability
- For use in low voltage ,high frequency inverters, free wheeling ,and polarity protection applications
- High temperature soldering guaranteed:260°C/10 seconds at terminals
- Lead-free parts meet environmental standards of MIL-STD-19500 /228
- Suffix "-H" indicates Halogen-free parts, ex. SB220-H.

Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, DO-15
- Lead : Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- Mounting Position : Any
- Weight : Approximated 0.40 gram

Package outline



Maximum ratings and Electrical Characteristics (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.1	I _O			2.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I _{FSM}			50	A
Reverse current	V _R = V _{RRM} T _J = 25°C	I _R			0.5	mA
	V _R = V _{RRM} T _J = 100°C				10	
Thermal resistance	Junction to ambient Note 1	R _{θJA}		35		°C/W
Diode junction capacitance	f=1MHz and applied 4V DC reverse voltage	C _J		170		pF
Storage temperature		T _{STG}	-65		+175	°C

Note 1: Thermal resistance from junction to lead, and/or to ambient P. C. B. mounted with 0.375" (9.5mm) lead length with 1.5 X1.5"(38X38mm)copper pads

SYMBOLS	V _{RRM} ^{*1} (V)	V _{RMS} ^{*2} (V)	V _R ^{*3} (V)	V _F ^{*4} (V)	Operating temperature T _J , (°C)
SB220	20	14	20	0.55	-55 to +125
SB230	30	21	30		
SB240	40	28	40		
SB250	50	35	50	0.70	-55 to +150
SB260	60	42	60		
SB280	80	56	80	0.85	
SB2100	100	70	100		
SB2150	150	105	150		
SB2200	200	140	200	0.95	

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage@I_F=2.0A

Rating and characteristic curves (SB220 THRU SB2200)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

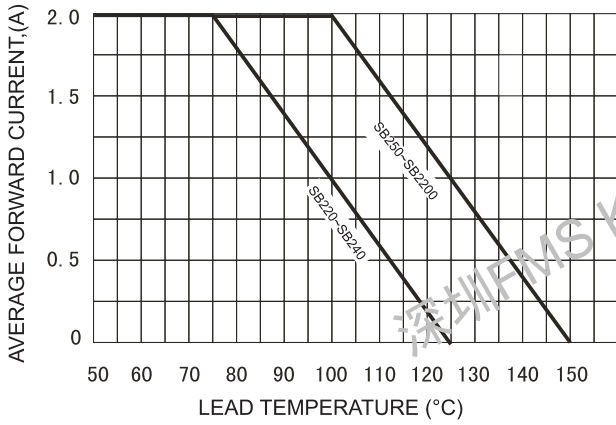


FIG.2-TYPICAL FORWARD CHARACTERISTICS

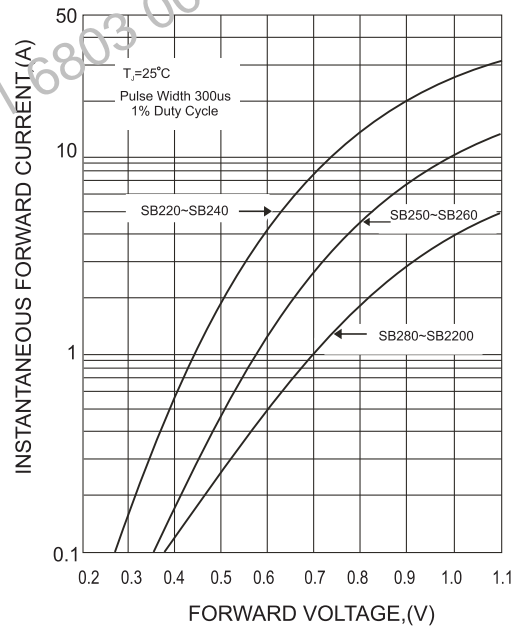


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

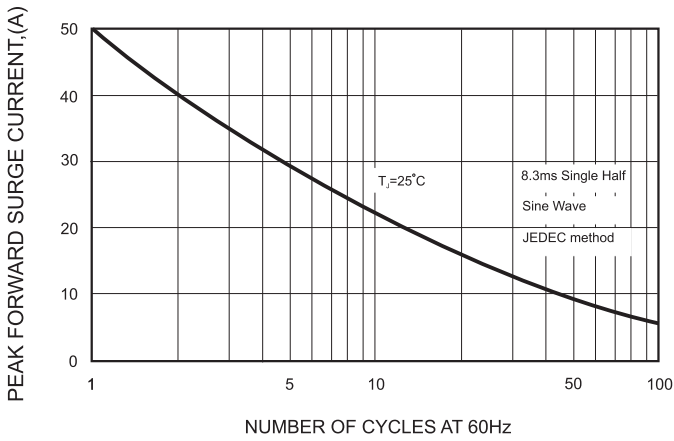


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

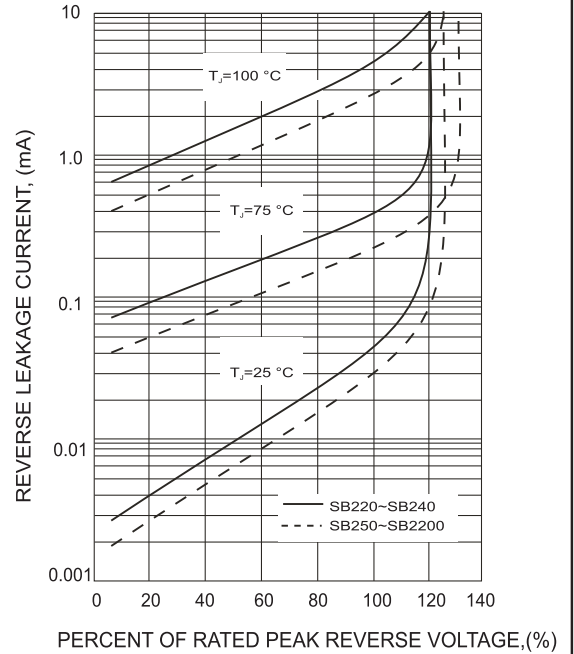
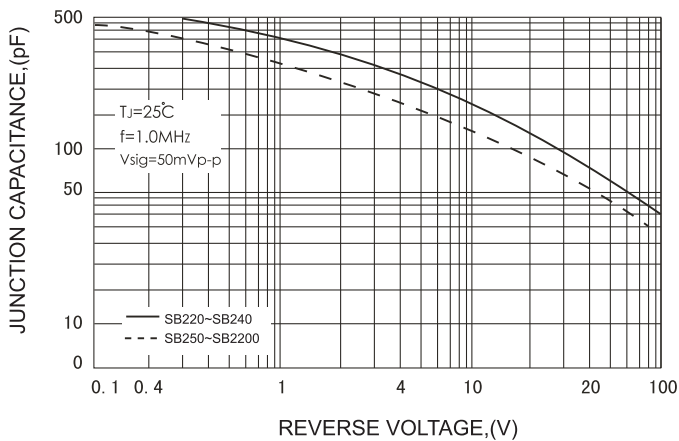




FIG.4-TYPICAL JUNCTION CAPACITANCE



SB220 THRU SB2200

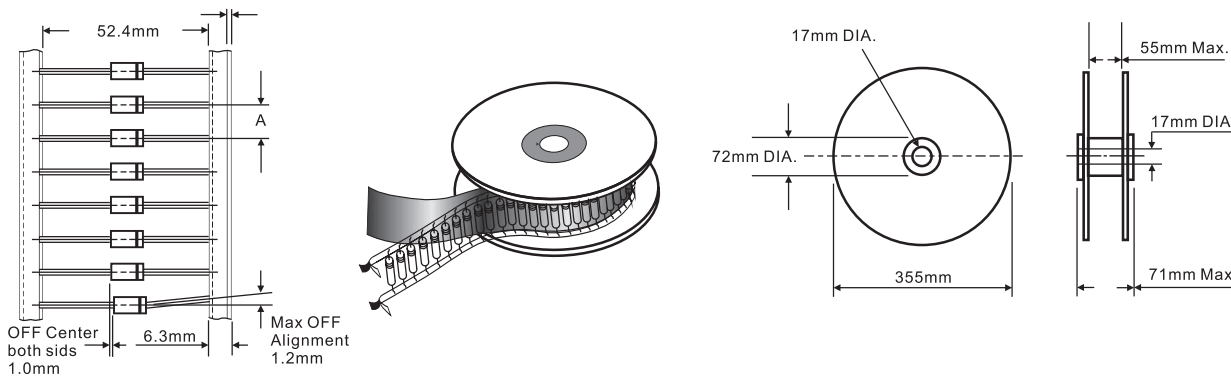
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
SB220	SB220
SB230	SB230
SB240	SB240
SB250	SB250
SB260	SB260
SB280	SB280
SB2100	SB2100
SB2150	SB2150
SB2200	SB2200

Taping & bulk specifications for AXIAL devices



REEL PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / REEL)	COMPONENT SPACING "A" in FIG. A	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	4,000	5 mm	360 * 340 * 370	16,000	9.9

AMMO PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	3,000	260 * 83 * 160	440 * 270 * 340	30,000	14.3

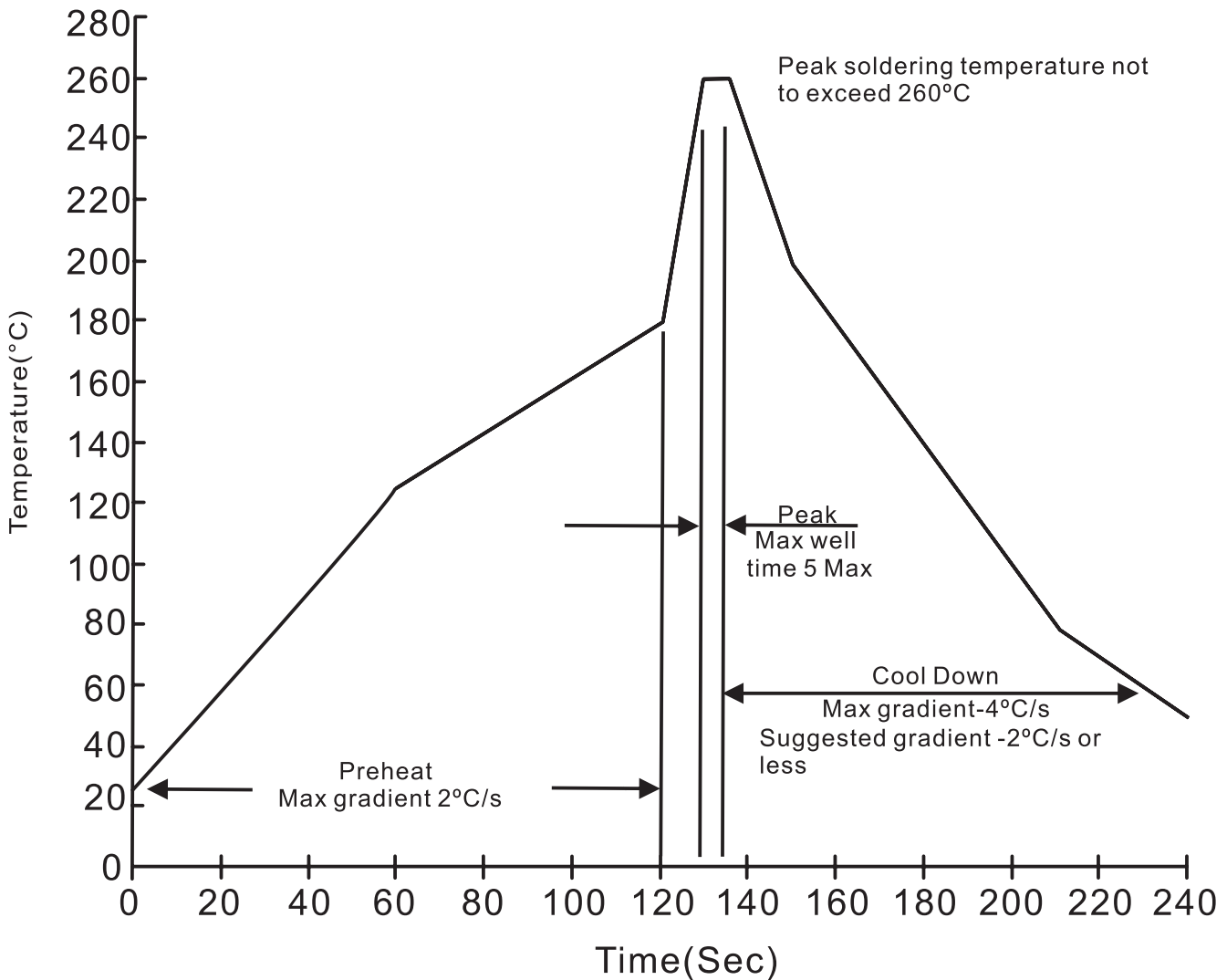
SB220 THRU SB2200

BULK PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
DO-15	500	194 * 84 * 20	465 * 220 * 260	25,000	12.9

Suggested thermal profiles for soldering processes

1. Lead free temperature profile wave-soldering



SB220 THRU SB2200**High reliability test capabilities**

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec. immerse body into solder 1/16"±1/32"	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. Pull Test	1.0kg in axial lead direction for 10 sec. $I_F = I_O$	MIL-STD-750D METHOD-2036
4. Bend Lead	1.0kg weight applied to each lead bending arc 90°±5° for 3 times.	MIL-STD-750D METHOD-2036
5. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 125^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
6. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
7. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min, on and off for 500 cycles.	MIL-STD-750D METHOD-1036
8. Pressure Cooker	15P _{sig} at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
9. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
10. Thermal Shock	0°C for 5 min. rise to 100°C for 5 min. total 10 cycles.	MIL-STD-750D METHOD-1056
11. Forward Surge	8.3ms single half sine-wave superimposed on rated load, one surge.	MIL-STD-750D METHOD-4066-2
12. Humidity	at $T_A = 85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
13. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031